Claims

1. A method of manufacture of an electronic assembly (8), the electronic assembly (8) comprising a circuit board and an electrical component (10), the method comprising the steps of:

laying a first terminal of the electrical component (10) upon a conductive region (12) of the circuit board, and providing solder paste (16) contacting the first terminal of the component (10) and the circuit board;

the method being characterised by the steps of: heating the solder paste (16) so as to liquefy the solder paste (16); thereby permitting a second terminal (18) of the component (10) to rise above the first terminal so as to erect the component (10) substantially perpendicular to the conductive region (12);

curing the liquefied solder paste (16) in order to fix the first terminal of the component (10) to the conductive region (12) of the circuit board.

2. A method according to Claim 1 further comprising the step of:

electrically connecting the second terminal (18) of the component (10) to a first terminal of an electrical device (24).

3. A method as claimed in any one of the preceding claims, wherein the second terminal (18) of the component (10) is gold plated.

4. A method as claimed in Claim 2 or Claim 3, wherein the electronic device (24) is an integrated circuit.

5. A method as claimed in Claim 2 or Claim 3, wherein the electronic device (24) is an electrical component.

6. An electronic assembly (8) comprising a conductive region (12), and an electrical component (10) having a first terminal at a first end and a second terminal (18) at a second end, the first terminal being fixed to the conductive region (12) and the second terminal (12) being disposed substantially perpendicular to the conductive region;

characterised in that:

the second terminal (12) is arranged to receive connecting means (20) for facilitating an electrical connection between the component (10) and an electronic device (24).

7. An electronic assembly (8) as claimed in Claim 6, wherein the second terminal (18) of the component (10) is gold plated.

8. An electronic assembly (8) as claimed in Claim 6 or Claim 7, wherein the connecting means (20) is a wire bond.

9. An electronic assembly (8) as claimed in any one of the claims 6 to 8, wherein the electronic device (24) is an integrated circuit or an electrical component.

10. A use of tombstoning in a method of manufacture of an electronic assembly (8).